

LINEAR TECHNOLOGY MATERIALS DECLARATION

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(Engineering Calculation)

DFN 3mm X 3mm Exp. Pad

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TOTAL MASS (g) : 0.02367

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001510	1000000	63792.8554688		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.009711	975000	410259.875		
		Iron (Fe)	7439-89-6	0.000239	24000	10097.0146484		
		Phosphorus (P)	7723-14-0	0.000003	300	126.740776062		
		Zinc (Zn)	7440-66-6	0.000007	700	295.728485107		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
Lead Frame Total:				0.009960	1000000	420779.375		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000455	1000000	19237.6738281		
		External Plating Total:				0.000455	1000000	19237.6738281
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000225	1000000	9505.55761719		
Internal Plating Total:				0.000225	1000000	9505.55761719		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000750	750000	31685.1914062		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000250	250000	10561.7314453		
Die Attach Total:				0.001000	1000000	42246.9257812		
Encapsulation	FILLED EPOXY RESIN	Resin (EP)		0.001153	110000	48710.703125		
		Bromine (Br)	40039-93-8	0.000105	10000	4435.92724609		
		Silica (SiO2)	60676-86-0	0.008908	850000	376335.59375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000314	30000	13265.5341797		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000000	0	0		
		Encapsulation Total:				0.010480	1000000	442747.75
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000040	1000000	1689.87695312		
					TOTAL MASS (g) :	0.02367		